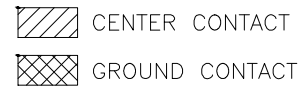
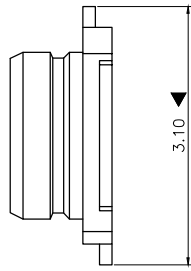
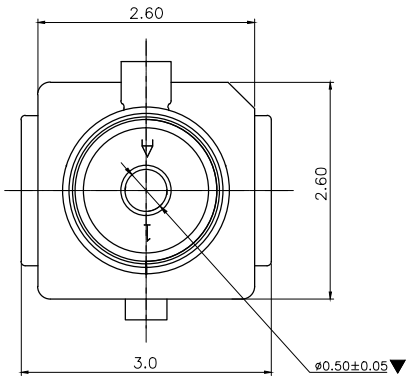
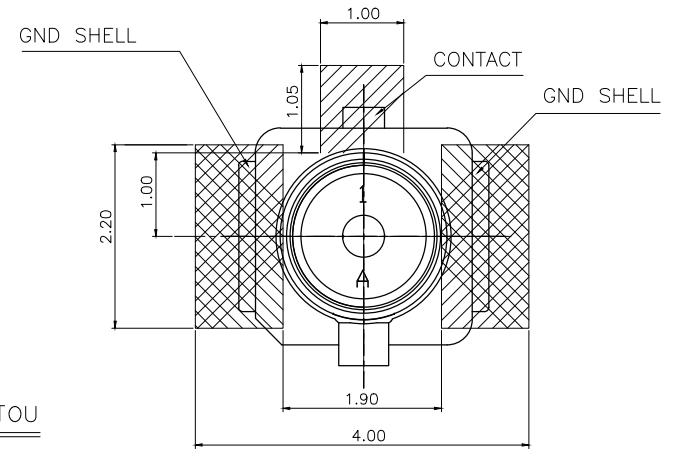


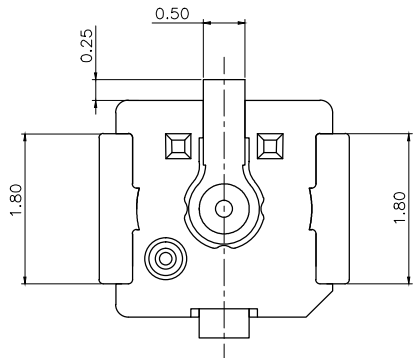
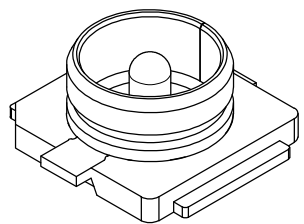
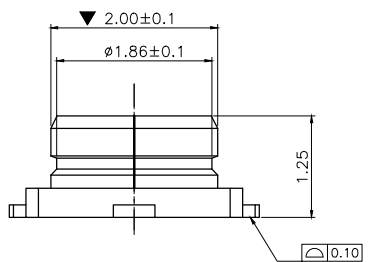
REV	ECN NO	DESCRIPTION	DATE	APPD
A		NEW RELEASE	2019.05.24	曾庆勇



RECOMMENDED PCB LAYTOU  
(TOLERANCE:  $\pm 0.05$ )



RECOMMENDED PCB LAYTOU  
(TOLFRANCF:  $\pm 0.05$ )



NOTE:

- HOUSING MATERIAL: THERMOPLASTIC, BLACK, UL 94V-0;  
CONTACT MATERIAL: COPPER ALLOY;  
GOLD PLATED: CONTACT AREA & SOLDER AREA  
SHELL MATERIAL: COPPER ALLOY;  
GOLD PLATED: CONTACT AREA&SOLDER AREA
- PERFORMANCE:
  - CONTACT RESISTANCE: 20mOHM Max.
  - DIELECTRIC WITHSTANDING VOLTAGE: 100V AC FOR 1MINUTE;
  - INSULATION RESISTANCE: 500MOHM Min.
- COPLANARITY: 0.1mm Max.
- APPLIED TO IR SOLDERING RROCESS.
- DIMEN SIONS MARKED ▼ AS THE FOCUS CONTROL SIZE

EXTEND USE		UNIT mm	TITLE		
RF1 BOARD CONN			RF1 BOARD CONN		
GENERAL TOLERANCE (M)		MATERIAL	APPD	DWG NO	
DIMENTION		QTY	CHD	19.002A7	
0.	/		石永涛	2019.05.24	
.0	$\pm 0.15$		朱春辉	2019.05.24	P/N:
.00	$\pm 0.10$	FINISHED	彭龙芳	2019.05.24	19.002A7-0001R0
.000	/				SHEET
					SCALE
					REV
					A